

## PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6485844

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
JI CUI	06/05/2020
FU-MING HUANG	04/06/2020
TING-KUI CHANG	04/06/2020
TANG-KUEI CHANG	06/05/2020
CHUN-CHIEH LIN	06/04/2020
WEI-WEI LIANG	06/03/2020
LIANG-GUANG CHEN	06/03/2020
KEI-WEI CHEN	06/03/2020
HUNG YEN	06/03/2020
TING-HSUN CHANG	06/04/2020
CHI-HSIANG SHEN	06/04/2020
LI-CHIEH WU	06/03/2020
CHI-JEN LIU	06/03/2020

**RECEIVING PARTY DATA**

<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.
<b>Street Address:</b>	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN

**PROPERTY NUMBERS Total: 1**

Property Type	Number
<b>Application Number:</b>	16902180

**CORRESPONDENCE DATA**

**Fax Number:**

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

**Phone:** 949 387 2885

**Email:** inbox@wpatca.com

**Correspondent Name:** WPAT, PC INTELLECTUAL PROPERTY ATTORNEYS

**Address Line 1:** 1100 QUAIL STREET, SUITE 202

**Address Line 4:** NEWPORT BEACH, CALIFORNIA 92660

PATENT

<b>ATTORNEY DOCKET NUMBER:</b>	18506-1763
<b>NAME OF SUBMITTER:</b>	ANTHONY KING
<b>SIGNATURE:</b>	/Anthony King/
<b>DATE SIGNED:</b>	01/08/2021
<b>Total Attachments: 4</b> source=US10165_Assignment#page1.tif source=US10165_Assignment#page2.tif source=US10165_Assignment#page3.tif source=US10165_Assignment#page4.tif	

## ASSIGNMENT

WHEREAS, I(we), CUI, JI, HUANG, FU-MING, CHANG, TING-KUI, CHANG, TANG-KUEI, LIN, CHUN-CHIEH, LIANG, WEI-WEI, CHEN, LIANG-GUANG, CHEN, KEI-WEI, YEN, HUNG, CHANG, TING-HSUN, SHEN, CHI-HSIANG, WU, LI-CHIEH and LIU, CHI-JEN whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled

### **METHODS FOR CHEMICAL MECHANICAL POLISHING AND FORMING INTERCONNECT STRUCTURE**

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

☐ United States Design Patent was

☐ executed on:

☒ filed on: 15 June 2020

Serial No.: 16/902,180

☐ established by PCT International Patent Application No.:

filed:

designating the

United States of America

☐ issued on \_\_\_\_\_ as U.S. Patent No.: \_\_\_\_\_

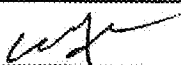
WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD. whose post office address is NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

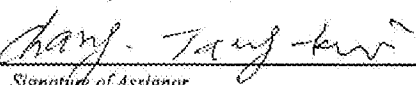
ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

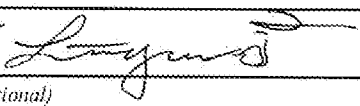
Assignor Name CUI, JI	Address 557 STRONG ST, BOLINGBROOK, IL 60440, U.S.A.
Signature of Assignor (X) 	Date of Signature (X) 06/05/2020
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

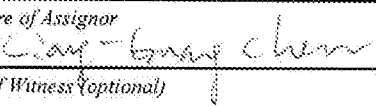
Assignor Name HUANG, FU-MING	Address NO.30-1, SHIGU RD., SHENGANG TOWNSHIP, CHANGHUA COUNTY 509, TAIWAN (R.O.C.)
Signature of Assignor (X) HUANG, FU-MING	Date of Signature (X) 04.06.2020
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

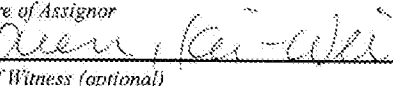
Assignor Name CHANG, TING-KUI	Address 4F., NO.18, LN.21, SANMIN RD., XINDIAN DIST., NEW TAIPEI CITY 231, TAIWAN (R.O.C.)
Signature of Assignor (X) CHANG, TING-KUI	Date of Signature (X) 04.06.2020
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

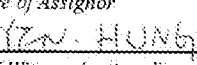
Assignor Name CHANG, TANG-KUEI	Address NO.177, ANNAN RD., JIALI DIST., TAINAN CITY 72259, TAIWAN (R.O.C.)
Signature of Assignor (X) 	Date of Signature (X) 2020.6.5
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

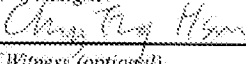
Assignor Name LIN, CHUN-CHIEH	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C.
Signature of Assignor (X) LIN, CHUN-CHIEH	Date of Signature (X) 2020/6/4
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name LIANG, WEI-WEI	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C.
Signature of Assignor (X) 	Date of Signature (X) 2020/6/3
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name CHEN, LIANG-GUANG	Address NO.393, SEC. 2, GONGDAO 5TH RD., EAST DIST., HSINCHU CITY 300, TAIWAN (R.O.C.)
Signature of Assignor (X) 	Date of Signature (X) 2020/6/3
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name CHEN, KEI-WEI	Address NO.3, LN. 188, YUPING RD., EAST DIST., TAINAN CITY 701, TAIWAN (R.O.C.)
Signature of Assignor (X) 	Date of Signature (X) 2020/6/3
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name YEN, HUNG	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C.
Signature of Assignor (X) 	Date of Signature (X) 2020/6/3
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name CHANG, TING-HSUN	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C.
Signature of Assignor (X) 	Date of Signature (X) 2020.06.03
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name SHEN, CHI-HSIANG  S	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C.
Signature of Assignor (X) SHEN, CHI-HSIANG	Date of Signature (X) 2020/06/04
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name WU, LI-CHIEH	Address 16F.-5, NO.1, LN. 175, WULING RD., NORTH DIST., HSINCHU CITY 300, TAIWAN (R.O.C.)
Signature of Assignor (X) WU, LI-CHIEH	Date of Signature (X) 2020/06/03
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name LIU, CHI-JEN	Address RM.2, 13F., NO.6, ALY. 62, LN. 411, SEC.1 NEIHU RD., NEIHU DIST., TAIPEI CITY 114, TAIWAN (R.O.C)
Signature of Assignor (X) Liu Chi-Jen	Date of Signature (X) 2020/06/03
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)